

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component comprising: ~~steps of~~

positioning a multi-layered unit formed on a support sheet ~~and including, wherein the multi-layered unit includes~~ a release layer, an electrode layer and a ceramic green sheet, so that a surface of the multi-layered unit is located on a base substrate,;

pressing the multi-layered unit toward the base substrate; and

laminating the multi-layered unit on the base substrate, wherein the base substrate has such surface roughness as to include per  $0.01\text{ mm}^2$  thereof not more than one protrusion that can penetrate the ceramic green sheet of the multi-layered unit laminated on the base substrate to half or more ~~the-a~~ thickness of the ceramic green sheet and include per  $100\text{ mm}^2$  thereof not more than one protrusion that can completely penetrate the ceramic green sheet.

2. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein an agglutinant layer is formed on the base ~~sheet substrate~~ and the multi-layered unit is positioned on the base substrate so that the surface of the multi-layered unit comes into contact with ~~the-a~~ surface of the agglutinant layer and pressed toward the base substrate, thereby laminating the multi-layered unit on the base substrate.

3. (Canceled)

4. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer is

formed on ~~the-a~~ surface of the base ~~sheet~~ substrate in such a manner that ~~the-a~~ bonding strength between itself and the base substrate is higher than ~~the-a~~ bonding strength between the support sheet and the release layer and lower than ~~the-a~~ bonding strength between itself and the ceramic green sheet.

5. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer has a thickness of 0.01  $\mu\text{m}$  to 0.3  $\mu\text{m}$ .

6. (Canceled)

7. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer has a thickness of 0.01  $\mu\text{m}$  to 0.3  $\mu\text{m}$ .

8. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a binder belonging to ~~the-a~~ same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

9. (Canceled)

10. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains a binder belonging to ~~the-a~~ same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

11. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer

contains a plasticizing agent belonging to the same binder group as that of a plasticizing agent contained in the ceramic green sheet ~~belongs to~~.

12. (Canceled)

13. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains a plasticizing agent belonging to ~~the—a~~ same binder group as that of a plasticizing agent contained in the ceramic green sheet ~~belongs to~~.

14. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains dielectric particles having ~~the—a~~ same composition as that of dielectric particles contained in the ceramic green sheet.

15. (Canceled)

16. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains dielectric particles having ~~the—a~~ same composition as that of dielectric particles contained in the ceramic green sheet.

17. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

18. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the base substrate is formed of a plastic material

selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

19. (Canceled)

20. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

21. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a said thickness equal to or thinner than 3  $\mu\text{m}$ .

22. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the ceramic green sheet has a said thickness equal to or thinner than 3  $\mu\text{m}$ .

23. (Canceled)

24. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the ceramic green sheet has a said thickness equal to or thinner than 3  $\mu\text{m}$ .